

Mitsubishi Chemical Increases Production Capacity of Special Epoxy Resins for  
Semiconductor Encapsulants and Electronic Materials

Mitsubishi Chemical Corporation

Mitsubishi Chemical Corporation (MCC; Head office: Chiyoda-ku, Tokyo; President: Masayuki Waga) hereby announces that it has decided to build a new facility for producing specialty epoxy resins for semiconductor encapsulants and electronic materials at its Fukuoka Plant (Kitakyushu-shi, Fukuoka).

Epoxy resins are used for a variety of applications such as paints, adhesives, and semiconductor encapsulants. Particularly, MCC specialty epoxy resins have excellent properties such as high heat resistance, low melt viscosity, and low water absorption, and some of them have been adopted as the de facto standard specially for semiconductor encapsulants all over the world; the semiconductor market is expected to grow significantly in the future.

MCC currently produces epoxy resins at its Mie Plant (Yokkaichi-shi, Mie). In order to meet the strong demand of the semiconductor market and strengthen the supply capability, MCC has decided to establish a new production line as follows.

Note that Shinryo Corporation (Head office: Kitakyushu-shi, Fukuoka; President: Toshiro Eto), MCC's group company, will undertake production.

With this enhancement, MCC's production capacity of specialty epoxy resins for semiconductor encapsulants and electronic materials will be increased by around 30% compared to the current capacity. MCC will keep considering for further enhancement of production capability to strengthen the epoxy business.

1. Location: Fukuoka Plant, Mitsubishi Chemical Corporation (production at Shinryo Corporation)
2. Start of commercial production: April 2023 (planned)
3. Product: Special epoxy resins for semiconductor encapsulants and electronic materials



Fukuoka Plant, Mitsubishi Chemical



Specialty epoxy resins

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